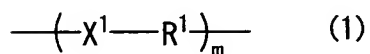


ABSTRACT

A resin composition which is excellent in quick curing and can be used for curing in conventionally used ovens, and a semiconductor device which is excellent in reliability such as solder crack resistance or the like when the resin composition is used as a die attach material for semiconductor. Further preferably, a resin composition which has a sufficient low stress property, good adhesion and excellent bleeding property.

A resin composition comprising a filler (A), the compound (B) comprising a structure represented by the formula (1) and a functional group represented by the formula (2) and a thermal radical initiator (C), and substantially not containing a photo polymerization initiator.

Formula (1):



Formula (2):

